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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N: **CL31F104ZACNBND**
- Description : **CAP,100nF, -20+80%, 25V, Y5V, 1206**

## A. Samsung Part Number

CL   31   F   104   Z   A   C   N   B   N   D  
 ①   ②   ③   ④   ⑤   ⑥   ⑦   ⑧   ⑨   ⑩   ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	1206 (inch code)	L: 3.2 ± 0.15 mm	W: 1.6 ± 0.15 mm
③ Dielectric	Y5V	⑧ Inner electrode	Ni
④ Capacitance	100 nF	Termination	Cu
⑤ Capacitance tolerance	-20/+80 %	Plating	Sn 100% (Pb Free)
⑥ Rated Voltage	25 V	⑨ Product	Array(4-element)
⑦ Thickness	0.85 ± 0.15 mm	⑩ Special	Reserved for future use
		⑪ Packaging	Cardboard Type,13"reel(10,000ea)

## B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz±10%      1.0±0.2Vrms
Tan δ (DF)	0.05 max.	
Insulation Resistance	More than 500Mohm·μF	Rated Voltage      60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characteristics	Y5V (From -30°C to 85°C, Capacitance change should be within -80~+22%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g·F, for 10±1 sec.
Bending Strength	Capacitance change : within ±30%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±20% Tan δ, IR : initial spec.	Solder pot : 270±5°C, 10±1sec.

	Performance	Test condition
<b>Vibration Test</b>	Capacitance change : within $\pm 20\%$ Tan $\delta$ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
<b>Moisture Resistance</b>	Capacitance change : within $\pm 30\%$ Tan $\delta$ : 0.075 max IR : More than $25M\Omega \cdot \mu F$	With rated voltage $40 \pm 2^\circ C$ , 90~95%RH, 500+12/-0 hours
<b>High Temperature Resistance</b>	Capacitance change : within $\pm 30\%$ Tan $\delta$ : 0.075 max IR : More than $50M\Omega \cdot \mu F$	With 200% of the rated voltage Max. operating temperature  1000+48/-0 hours
<b>Temperature Cycling</b>	Capacitance change : within $\pm 20\%$ Tan $\delta$ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^\circ C$ $\rightarrow$ Max. operating temperature $\rightarrow 25^\circ C$  5 cycles test

**C. Recommended Soldering method :**

Reflow ( Reflow Peak Temperature :  $260 \pm 0/-5^\circ C$ , 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.